Šir: Fransmitted herewith for filing is the Patent Application of: ventor: CHAOYONG LI, DAO HUA ZHANG For: METHOD TO FORM CU SEED LAYER FOR CU INTERCONNECT ö Enclosed are: 5 sheets of drawing(s) - Informal An assignment of the invention to Agency For Science, Technology And Research Applicant claims small entity status An associate power of attorney Request & Certification under 35 USC 122(b)(2)(b)(i) The filing fee has been calculated as shown below: OTHER THAN A SMALL ENTITY (Col. 1) (Col. 2) FOR: NO. FILED NO. EXTRA RATE FEE BASIC FEE \$ 750. x 18 =\$ 216. INDEP_CLAIMS $\times 84 =$ \$ 0. **SUB TOTAL** \$ 966. ASSIGNMENT \$40. TOTAL \$ 1.006 Please charge my Deposit Account No. 19-0033 in the amount of \$ 1,006. A duplicate copy of this sheet is enclosed. The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 19-0033. A duplicate copy of this sheet is enclosed.

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Any additional filing fees required under 37 CFR §1.16.

Any patent application processing fees under 37 CFR §1.17.

8 August 2003

Date of deposit

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